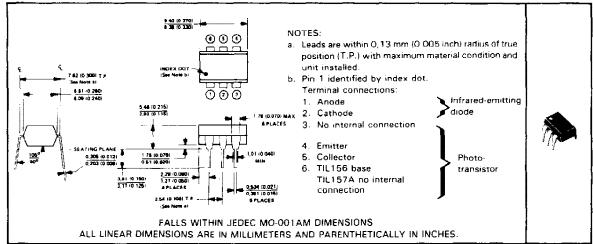
#### UL LISTED - FILE #E65085

- GaAs-Diode Light Source Optically Coupled to a Silicon N-P-N Darlington-Connected Phototransistor
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- Plug-In Replacement for TIL113 and TIL119A
- High-Voltage Electrical Isolation . . . 2500 V RMS (3535 V Peak)
- No Base Connection on TIL157A for Environments with High Electromagnetic Interference

#### mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon darlington-connected phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high humidity conditions. Unit weight is approximately 0.52 grams.



## absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output RMS Voltage (See Note 1)	2500 V
Collector-Base Voltage (TIL156)	30 V
Collector-Emitter Voltage (See Note 2)	30 V
Emitter-Collector Voltage	7 V
Emitter-Base Voltage (TIL156)	7 V
Input-Diade Reverse Voltage	3 V
Input-Diode Continuous Forward Current at (or below) 25°C Free-Air Temperature (See Note 3) 1	100 mA
Continuous Phototransistor Power Dissipation at (or below) 25°C Free-Air Temperature (See Note 4) 1	
Storage Temperature Range	150°C
Lead Temperature 1,6 mm (1/16 inch) from Case for 10 Seconds	

- NOTES 1. This rating applies for sine-wave operation at 50 or 60 Hz, Service capability is verified by testing in accordance with UL requirements.
  - 2. This value applies when the base emitter diode is open-circuited.
  - 3. Denate linearly to 100°C free-air temperature at the rate of 1.33 mA/°C.
  - 4. Denate linearly to 100°C free-air temperature at the rate of 2 mW/°C.



## TIL158, TIL157A OPTOCOUPLERS

## electrical characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS <sup>†</sup>			TIL156			TIL157A			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	UNIT
V(BR)CBO	Collector-Base Breakdown Voltage	I <sub>C</sub> = 10 μA,	I <sub>E</sub> = 0,	IF - 0	30						٧
V(BR)CEO	Collector-Emitter Breakdown Voltage	IC = 1 mA,	(g = 0,	IF=0	30			30			٧
V(8R)EBO	Emitter-Base Breakdown Voltage	ig = 10 μA,	IC = 0.	1F = 0	7						v
V <sub>(BR)ECO</sub>	Emitter-Collector Breakdown Voltage	lE = 10 μA,	l <b>F</b> * 0					7			V
I <sub>R</sub>	Input Diode Static Reverse Current	V <sub>R</sub> = 3 V					10			10	μА
<sup>†</sup> C(on)	On-State Collector Current	V <sub>CE</sub> = 1 V, V <sub>CE</sub> = 1 V,	lg = 0, lg = 10 mA	lp = 10 mA	30	100		30	160		mA
<sup>1</sup> C(off)	Off-State Collector Current	V <sub>CE</sub> = 10 V,	IB = 0,	IF = 0			100			100	nA
hFE	Transistor Static Forward Current Transfer Ratio	V <sub>CE</sub> = 1 V,	I <sub>C</sub> = 10 mA,	IF = 0		15 000					
٧F	Input Diode Static Forward Voltage	I <sub>F</sub> = 10 mA					1.5			1.5	٧
VCE(sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 125 mA, I <sub>C</sub> = 30 mA,	I <sub>B</sub> ≠ 0, I <sub>F</sub> = 10 mA	1 <sub>F</sub> = 50 mA			1.2			1	\ v
10	Input-to-Output Internal Resistance	V <sub>in-out</sub> = 500 V,	See Note 5		1011			1011			Ω
Cio	Input-to-Output Capacitance	V <sub>in-out</sub> ≠ 0,	f = 1 MHz,	See Note 5		1	1.3		1	1.3	pF

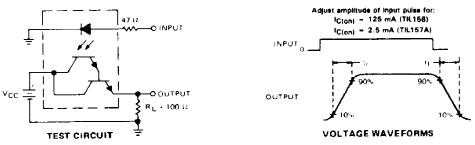
Note 5: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

†References to the base are not applicable to the TIL157A.

## switching characteristics at 25°C free-air temperature

PARAMETER			TEST SOURIFICANS!		TIL156			TIL157A		
		168	TEST CONDITIONS <sup>†</sup>			MAX	MIN	TYP	MAX	UNIT
tr	Rise Time	V <sub>CC</sub> = 15 V,	IC(on) = 125 mA,		300					
tr	Fall Time	R <sub>L</sub> = 100 Ω.	See Figure 1		300					με
tr	Rise Time	V <sub>CC</sub> = 10 V,	I <sub>Clan)</sub> = 2.5 mA.				ľ	300		
tį	Fall Time	R <sub>L</sub> = 100 Ω.	See Figure 1		-			300		μš

## PARAMETER MEASUREMENT INFORMATION



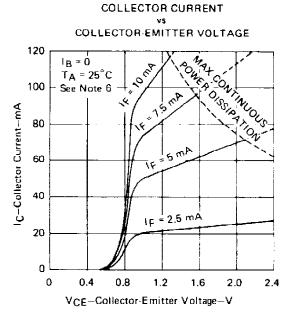
NOTES: a. The input waveform is supplied by a generator with the following characteristics:  $Z_{\text{out}} \sim 50 \, \Omega_c$ ,  $\tau_r \approx 15 \, \text{ns}$ , duty cycle  $\approx 1\%$ ,

FIGURE 1-SWITCHING TIMES

 $t_W=500~\mu s$ . b. The output waveform is monitored on an oscilloscope with the following characteristics:  $t_r \le 12~ns$ ,  $R_{in} \ge 1~M\Omega$ ,  $C_{in} \le 20~pF$ .

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#### TYPICAL CHARACTERISTICS

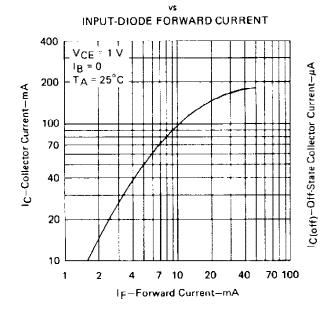


**COLLECTOR CURRENT COLLECTOR-EMITTER VOLTAGE** 200 180 160 1F = 30 mA IC-Collector Current-mA = 40 mA 120 | F = 50 mA 100 80 60 40 1<sub>B</sub> = 0  $T_A = 25^{\circ}C$ 20 See Note 6 0 0.2 0.4 0.6 0.8 1 1.2 1.4 1.6 1.8 2 VCE-Collector-Emitter Voltage-V

FIGURE 2

COLLECTOR CURRENT

FIGURE 3



# OFF-STATE COLLECTOR CURRENT vs FREE-AIR TEMPERATURE

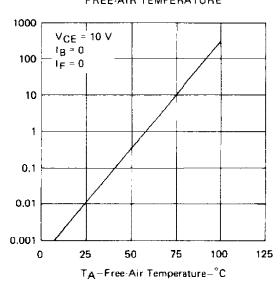


FIGURE 4

FIGURE 5

NOTE 6. Pulse operation of input diode is required for operation beyond limits shown by dotted line.

## TYPICAL CHARACTERISTICS

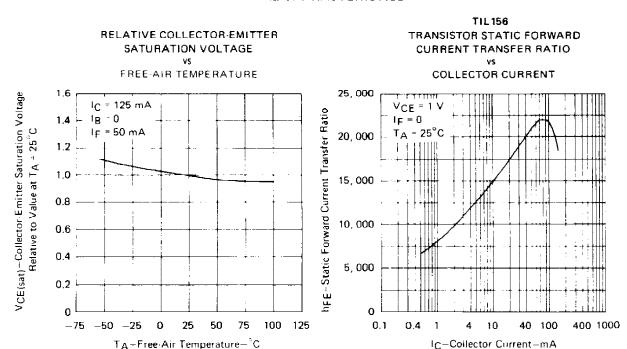
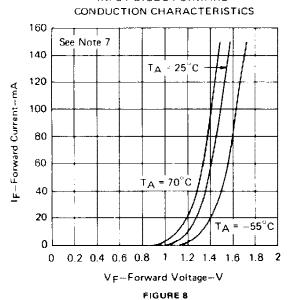


FIGURE 6
INPUT DIODE FORWARD



NOTE 7: This parameter was measured using pulse techniques,  $t_{\rm W} = 1~{\rm ms}$ , duty cycle  $\leq 2\%$ .

FIGURE 7

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## PACKAGE OPTION ADDENDUM

8-Apr-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TIL156	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL157A	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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